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TIAN(10) **Pub. No.: US 2022/0361384 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **SHIELDING FILM HAVING
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ABSTRACT

A shielding film having a multi-layered metal structure is provided, including an insulating layer and a multi-layered metal compounded on the insulating layer, wherein the thickness of each layer of metal is 0.05-5 μm , the multi-layered metal has 2-10 layers, and a conductive bonding layer is disposed between the multi-layered metal. In the present application, the thickness of each layer of metal is controlled by providing a multi-layered metal, and a conductive bonding layer is bonded between the layers of metal such that the shielding film has good flexibility and shielding effect. Additionally, the conductive bonding layer is used so that the binding force between the layers of metal is good, and a high-frequency signal shielding performance of greater than 80db@10ghz is ensured so that the shielding film has good flexibility and meets flexibility requirements for flexible circuit boards while also having good high-temperature resistance.

